

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	5211	((conductive electrode circuit board) adj2 (adhesive paste paint ink) (hole via) adj2 fill adj2 (adhesive paste) and (copper Cu silver Ag Pd palladium metal alloy) near5 (powder particle) and (particle grain) near5 (size diameter micron "mu.m") and (wt weight vol volume mass) near5 ("% \$2% percent ratio part) and (resin binder epoxy (alkyd phenol thermoset\$5 epoxy) near5 resin epi\$2ote)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:06
S2	271	S1 and (primary unimodal monodispersed) near5 particle and (agglomerat\$4 floc aggregate cluster) near5 (powder particle grain)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:08
S3	66	S1 and (nano\$2particle nanoparticle micro\$2particle) with (core surface) with particle	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:08
S4	364	S1 and (powder particle slurry) with (jet adj mill dry adj2 grinding air adj classifier turbo adj classifier colli \$5 near5 dispersion high adj pressure homogeni\$2er)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:09
S5	94	S1 and (copper Cu silver Ag Pd palladium metal alloy Ni nickel) with (wet adj2 reduction reduction near5 solution)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:10
S6	1053	S1 and (252/500,503,512-514.ccls. 75/255.ccls. 428/209,313.5,356,355ep,357,402,403.ccls. 156/306.3.ccls. 361/748,760.ccls. 427/97.2,97.3,97.7.ccls. 213/13,311,319.ccls. 257/62.ccls. 174/259,262.ccls.)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:15
S7	23	S1 and dimer\$3 with (ether ester\$7) with (\$3glycidyl epoxy) and amine same (adduct curing harden\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:16
S8	49	S2 and S6	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:16

S9	13	S3 and S6	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:17
S10	63	S4 and S6	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:17
S11	44	S5 and S6	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:17
S12	156	S6 and (liquid adj2 epoxy alicyclic adj epoxy glycidyl adj amine glycidyl adj ester epi\$2ote)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:18
S13	159	S6 and (particle powder) near5 (surface coat\$4 plat\$4 clad) with alloy	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:19
S14	563	S6 and (particle powder) near5 (surface coat\$4 plat\$4 clad) with (metal alloy)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:19
S15	323	S6 and viscosity near5 (\$7poise \$7pascal pa\$2 mpa\$2 cps low)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 16:22
S16	22	((conductive electr\$conductive electrode board) adj2 (adhesive paste paint ink) (hole via) adj2 fill) and (conductive near5 filler copper Cu silver Ag metal alloy) and (primary) and (agglomerat\$4 floc aggregat \$4)	EPO; JPO; DERWENT	OR	ON	2008/06/06 16:23
S17	13	((yuichiro near2 sugita toshiaki near2 takenaka).in. matsushita.as.) and (copper silver metal alloy) and (primary near5 particle) and (agglomerat\$5 floc aggregate) and (conductive via adj fill hole adj fill) near5 (adhesive paste)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/06 16:24
S18	36	("06262375" "07176846" "08279665" "2000297303" "2002332501" "2002343135" "2003092024" "2003141929" "2003268402" "2004047856" "6479763" "6494931" "20030122257" "20010005545" "5551626"). did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/06/06 16:24
S19	131	polyester with thermosetting and (aromatic alicyclic) adj2 dicarboxylic adj acid and alkylene adj glycol and (polyalkylene adj glycol PEG polyhydric adj alcohol)	US-PGPUB; USPAT	OR	ON	2008/06/06 17:00

6/ 6/ 2008 6:28:45 PM

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